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automatically adjusting an amount of the resin extruded from the resin application device based on the external appearance a surface area of the resin obtained in the imaging step.

Please CANCEL claim 2.

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3. (ONCE AMENDED) the resin coating method as claimed in claim 1, wherein the imaging step comprises:

exposing the resin to light of a predetermined wavelength so as to fluoresce the resin;

and

separating fluorescent light so generated from light of other wavelengths to obtain a fluorescent image of the resin.

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6. (ONCE AMENDED) A resin coating method for applying resin to a predetermined amount of resin region of on a printed wiring board, comprising the steps of: imaging an external appearance of a resin drop after the resin drop has been extruded from a nozzle of a resin application device but before the resin drop contacts the printed wiring board; and

adjusting a distance between a tip of the nozzle and the printed wiring board based on the external appearance of the resin drop obtained in the imaging step.

7. (ONCE AMENDED) A resin coating method for applying a predetermined amount of resin to a predetermined region of on a printed wiring board, comprising the steps of: imaging a residual amount of the resin on an extrusion nozzle of a resin application device from which the resin is expelled; and

washing the nozzle when the residual amount exceeds a predetermined amount.

Please add the following NEW claims:

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13. (NEW) A resin coating method as recited in claim 1, further comprising: applying the resin by extruding same from a nozzle of the resin application device, the extruded resin being in the form of a ball attached at a top part thereof to the nozzle and displaced above and separated from the printed wiring board.

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14. (NEW) A resin coating method as recited in claim 13, further comprising:

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lowering the nozzle so as to attach a bottom part of the ball to the printed wiring board and raising the nozzle so as to separate same from the ball.

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15. (NEW) A resin coating method as recited in claim 14, wherein the imaging is performed by measuring the diameter of the resin.

16. (NEW) A resin coating method as recited in claim 14, further comprising: spreading the resin ball to a uniform thickness layer; and determining the amount of the applied resin in accordance with the measured diameter and a correlation table relating to the latter to an amount.

17. (NEW) A resin coating method as recited in claim 6, further comprising: applying the resin by extruding same from a nozzle of the resin application device, the extruded resin being in the form of a ball attached at a top part thereof to the nozzle and displaced above and separated from the printed wiring board.

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18. (NEW) A resin coating method as recited in claim 17, further comprising: lowering the nozzle so as to attach a bottom part of the ball to the printed wiring board and raising the nozzle so as to separate same from the ball.

19. (NEW) A resin coating method as recited in claim 18, wherein the imaging is performed by measuring the diameter of the resin.

20. (NEW) A resin coating method as recited in claim 18, further comprising: spreading the resin ball to a uniform thickness layer; and determining the amount of the applied resin in accordance with the measured diameter and a correlation table relating to the latter to an amount.

21. (NEW) A resin coating method as recited in claim 7, further comprising: applying the resin by extruding same from the nozzle of the resin application device, the extruded resin being in the form of a ball attached at a top part thereof to the nozzle and displaced above and separated from the printed wiring board.